



Multi-Phase Flow and Heat Transfer

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Message from the Guest Editor

Thermal management plays critical role in a wide variety of electronical applications as their performance has increased and their physical space has decreased. As an efficient cooling method, two-phase heat transfer looks to be highly promising in the efficient thermal management of electronics to ensure their performance and reliability. However, many interdisciplinary scientific problems regarding two phase heat transfer still remain, including efficiency, reliability, durability, and the threshold of heat flux. Great efforts about two phase heat transfer enhancement have been made, such as rational designs for manipulating the liquid and vapor flow, wettability control for strengthening liquid supply, strategies for promoting the phase-change process, and so on. With the development of advanced theories and manufacturing techniques, novel two-phase heat transfer methods and their applications are continuously increasing. In this Special Issue, we welcome the contributions on two-phase heat transfer and their applications in the electronic field. We invite articles on theoretical and experimental studies on topics related to two-phase heat transfer.





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Message from the Editor-in-Chief

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